

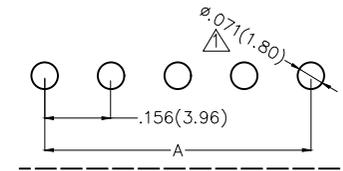
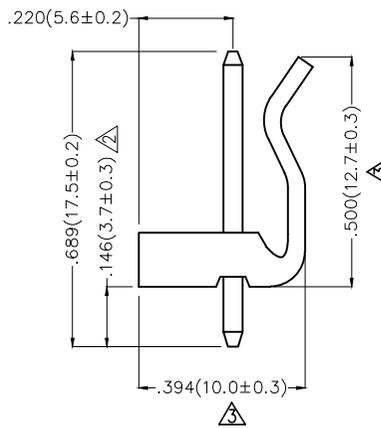
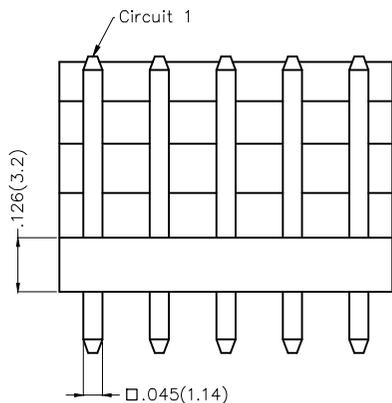
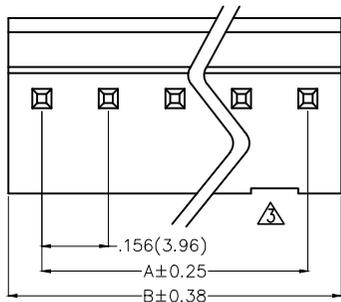
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Dimension $\phi.065(\phi 1.65)$ Change to $\phi.071(1.80)$	20150919	CHERRY	FAN
2		Size change	14/MAY/20	KATE	CHERRY
3		Structural and size changes	22/APR/21	KATE	JOHNNY

Electrical

Current Rating: 6A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 10 m Ω Max
Insulation Resistance: 1000 M Ω MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-0)
Contact Pin: Brass
Plating: Tin Plated

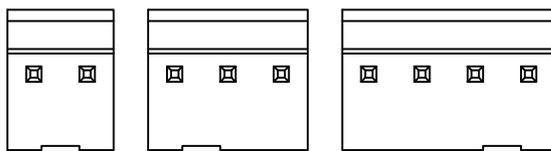


Recommended P.C.Board Layout

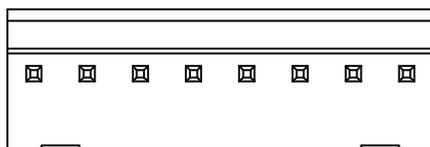
Ordering Information

FWF 396 03 - S XX S 2 2 T B
1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 396-Pitch 3.96mm	3 Distinction No. 03	4 Row Option S-Single Row	5 Circuits XX	6 Entry Angle S-180° Vertical
7 Plating 2-Tin Plated	8 Material-Resin 2-PA66	9 Color-Resin T-Transparent	10 Packaging B-PE Bag		



2 Circuits 3,6,7 Circuits 4,5 Circuits



8~12 Circuits

	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 19/SEP/15	PART NO. FWF39603-SXXS22TB	ITEM NO. FWF39603		
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X.'±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY CHERRY	DATE 19/SEP/15	TITLE Wire to Board (Wafer) Pitch 3.96mm 180° Vertical (DIP)		REV 3
SCALE 5:1	SIZE A4	DRAWN BY JACOB		DATE 19/SEP/15	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 1/2

1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

A

B

B

C

C

D

D

E

E

F

F

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF39603-S02S22TB	.156(3.96)	.311(7.92)
3	FWF39603-S03S22TB	.311(7.92)	.468(11.88)
4	FWF39603-S04S22TB	.468(11.88)	.624(15.84)
5	FWF39603-S05S22TB	.624(15.84)	.780(19.80)
6	FWF39603-S06S22TB	.780(19.80)	.935(23.76)
7	FWF39603-S07S22TB	.935(23.76)	1.091(27.72)
8	FWF39603-S08S22TB	1.091(27.72)	1.247(31.68)
9	FWF39603-S09S22TB	1.247(31.68)	1.403(35.64)
10	FWF39603-S10S22TB	1.403(35.64)	1.559(39.60)
11	FWF39603-S11S22TB	1.559(39.60)	1.715(43.56)
12	FWF39603-S12S22TB	1.715(43.56)	1.871(47.52)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 19/SEP/15	PART NO. FWF39603-SXXS22TB	ITEM NO. FWF39603	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20)	X.±5' X.±2'	CHECKED BY CHERRY	DATE 19/SEP/15	TITLE Wire to Board (Wafer) Pitch 3.96mm 180° Vertical (DIP)		REV 3
	SCALE 5:1	SIZE A4	X.XX±.006(0.15) X.XXX±.004(0.10)	DRAWN BY JACOB	DATE 19/SEP/15	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

1 2 3 4 5 6 7 8